



Discription

Low capacitance bidirectional ElectroStatic Discharge (ESD) protection diode in a DFN1006-2L(SOD-882) leadless ultra small Surface-Mounted Device (SMD) plastic package designed to protect one signal line from the damage caused by ESD and other transients.



DFN1006-2L

Features

- ★ Bidirectional ESD protection of one line
- ★ Low operating voltage: 3.3 V
- ★ Low clamping voltage $VC = 12V @7A$
- ★ Response time is typically <1ns
- ★ Ultra Low Leakage:nA Level
- ★ IEC 61000-4-2: level 4 (ESD)
- ★ IEC 61000-4-5 (surge): IPPMQ8 A



Circuit Diagram

Applications

- ★ Portable electronics
- ★ Computers and peripherals
- ★ Audio and video equipment
- ★ Cellular handsets and accessories
- ★ Communication systems
- ★ Power supplies

Ordering information

Product ID	Pack	Qty(PCS)
HESD9B3.3ST5G	DFN1006-2L	10000



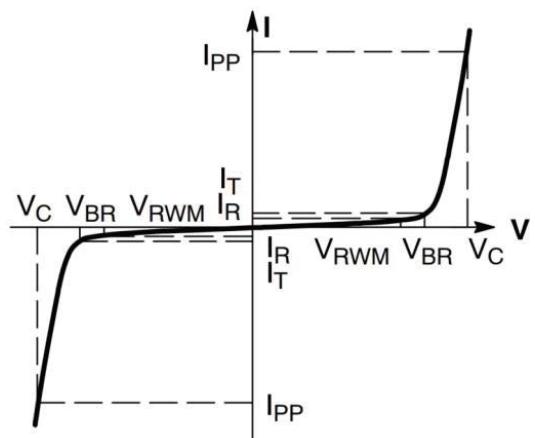
Absolute Ratings(Tamb = 25°C)

Parameter	Symbol	Value	Unit
Peak Pulse Power (tp = 8/20μs)	P _{PPM}	84	W
Maximum lead temperature for soldering during 10s	T _L	260	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Operating Temperature Range	T _{OP}	-55 to +150	°C
Maximum junction temperature	T _j	150	°C
ESD voltage IEC 61000-4-2 (air discharge)	V _{ESD}	15	kV
ESD voltage IEC 61000-4-2 (contact discharge)	V _{ESD}	8	kV

Electrical Characteristics

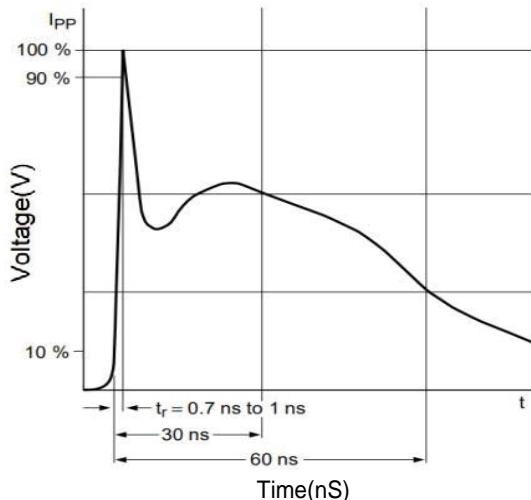
Parameter	Symbol	Min	Typ	Max	Unit	Condition
Reverse Working Voltage	V _{RWM}	--	--	3.3	V	
Breakdown Voltage	V _{BR}	3.6			V	I _T =1mA
Leakage Current I _{Leak}	I _R	--	--	1.0	uA	V _{RWM} =7.0V
Clamping Voltage	V _c	--		8.0	V	I _{PP} =1A, T _p =8/20μs
Clamping Voltage	V _c	--		12.0	V	I _{PP} =7A, T _p =8/20μs
Junction Capacitance	C _J	--	10.0	15.0	pF	V _R =0V, f=1MHz

Symbol	Parameter
I _{PPM}	Maximum Reverse Peak Pulse Current
V _c	Clamping Voltage @ I _{PP}
V _{RWM}	Working Peak Reverse Voltage
I _R	Reverse Leakage Current @ V _{RWM}
I _T	Test Current
V _{BR}	Breakdown Voltage @ I _T

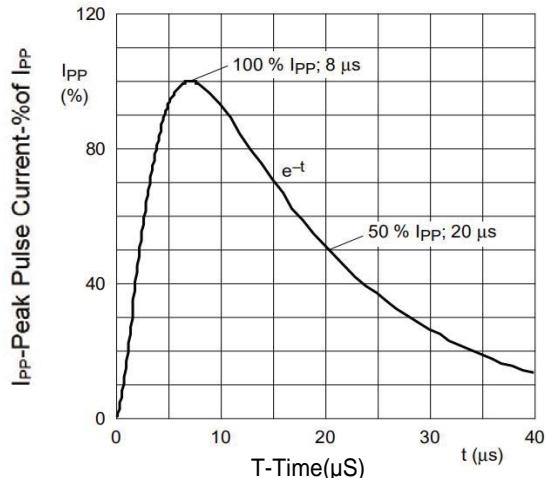




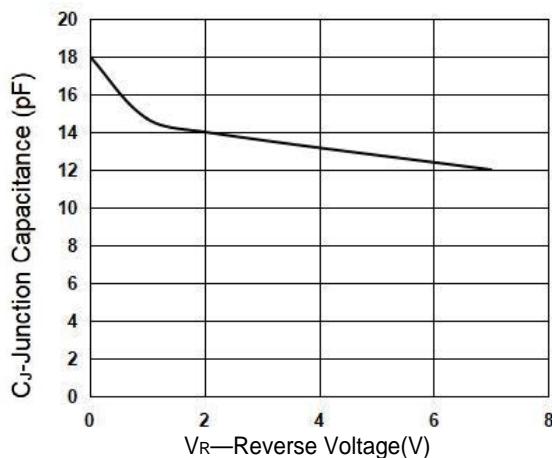
Typical Characteristics



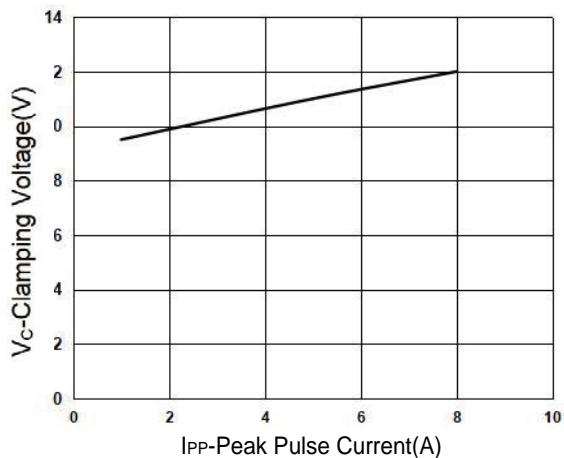
IEC61000-4-2 Pulse Waveform



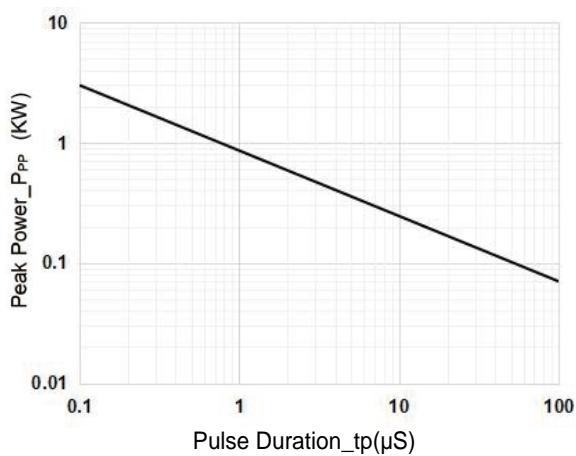
IEC61000-4-5 8X20μs Pulse Waveform



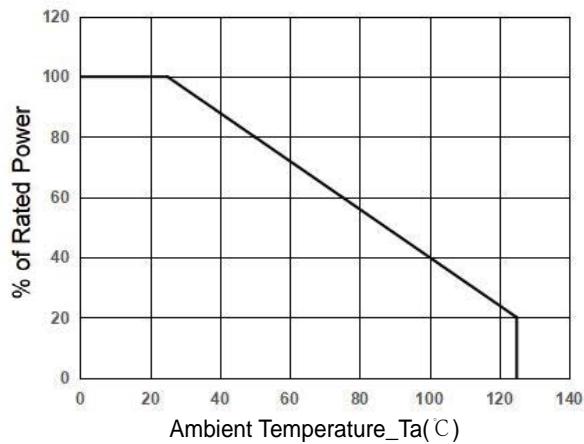
Junction Capacitance vs. Reverse Voltage



Clamping Voltage vs. Peak Pulse Current



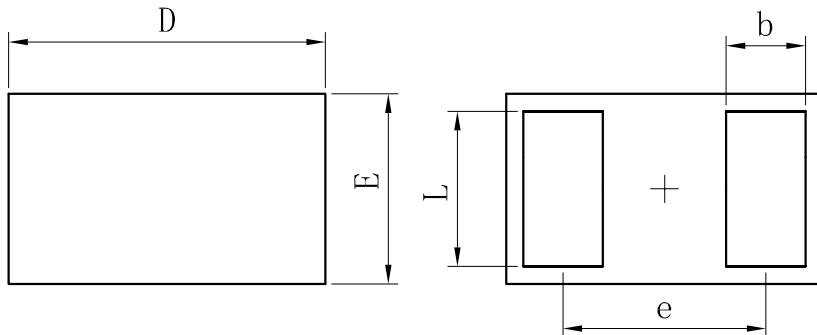
Peak Pulse Power vs. Pulse Time



Power Derating Curve

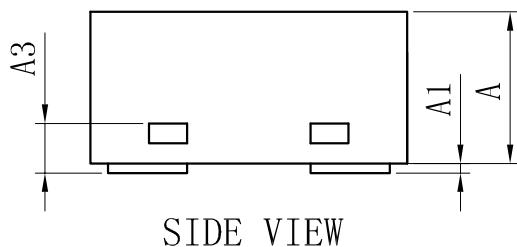


Outline And Dimensions



TOP VIEW

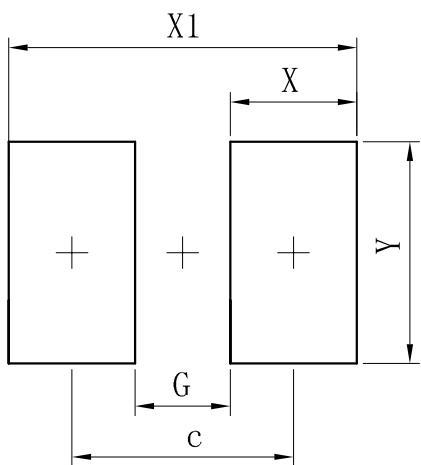
BOTTOM VIEW



SIDE VIEW

DFN1006-2L			
Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	—	0.64	—
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	—	0.05
A3	0.127REF.		
All Dimensions in mm			

Soldering Footprint



Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70



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